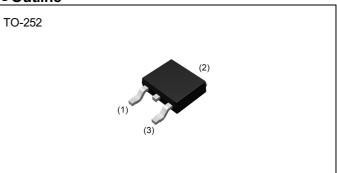
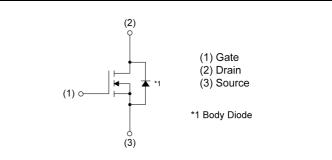


V <sub>DSS</sub>	600V
R <sub>DS(on)</sub> (Max.)	830mΩ
I <sub>D</sub>	±6A
P <sub>D</sub>	70W

#### ● Outline



#### Inner circuit



### Application

1) Low on-resistance

3) Parallel use is easy

2) Ultra fast switching speed

4) Pb-free plating ; RoHS compliant

Switching

Features

#### Packaging specifications

Packing	Embossed Tape
Packing code	TL1
Marking	R6006K
Basic ordering unit (pcs)	2500

#### • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain - Source voltage		V <sub>DSS</sub>	600	V
Continuous drain current (T <sub>c</sub> = 25	5°C)	۱ <sub>D</sub> *1	±6	А
Pulsed drain current	1 <sub>DP</sub> *2	±18	А	
static			±20	V
Gate - Source voltage AC(f>1Hz)		V <sub>GSS</sub>	±30	V
Avalanche current, single pulse		$I_{AS}^{*3}$	1.1	А
Avalanche energy, single pulse		E <sub>AS</sub> *3	65	mJ
Power dissipation ( $T_c = 25^{\circ}C$ )		P <sub>D</sub>	70	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and storage te	mperature range	T <sub>stg</sub>	-55 to +150	°C

#### •Thermal resistance

Deremeter	Cumph of	Values			Lincit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}^{*4}$	-	-	1.8	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	147	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## •Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions -		Values			Unit	
Parameter	Зупрог	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		600	-	-	V	
		V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V					
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μA	
		T <sub>j</sub> = 125°C	-	-	1000		
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	3.5	-	5.5	V	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.0A					
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	$T_j = 25^{\circ}C$	-	720	830	mΩ	
		$T_j = 125^{\circ}C$	-	1600	-		
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	3.4	-	Ω	



#### •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	C: make al	Conditions	Values			Linit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Admittance	Y <sub>fs</sub>  * <sup>5</sup>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 3.0A	1.5	3.0	-	S	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	350	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	350	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	20	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 300$ V, $V_{GS}$ = 10V	-	17	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 3.0A	-	22	-	20	
Turn - off delay time	$t_{d(off)}$ *5	$R_L \simeq 100\Omega$	-	30	-	ns	
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	30	-		

### • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Cump of	Conditions	Values			Unit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Offic
Total gate charge	Qg	V <sub>DD</sub> ≃ 300V	-	12	-	
Gate - Source charge	$Q_{gs}^{*5}$	I <sub>D</sub> = 6A	-	3.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	5.6	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 300V$ , $I_D = 6A$	-	6.2	-	V

\*1 Limited only by maximum channel temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L $\doteqdot$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>j</sub>=25°C

\*4 T<sub>C</sub>=25°C

\*5 Pulsed



#### •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Source current	۱ <sub>S</sub> *1	• T <sub>C</sub> = 25°C	-	-	6	А	
Pulsed source current	$I_{SP}^{*2}$	1 <sub>C</sub> - 25 C	-	-	18	А	
Source-Drain voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 6A	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5		-	290	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	I <sub>S</sub> = 6A di/dt = 100A/µs	-	2.2	-	μC	
Peak reverse recovery current	۱ <sub>۳</sub> *5		-	15	-	А	





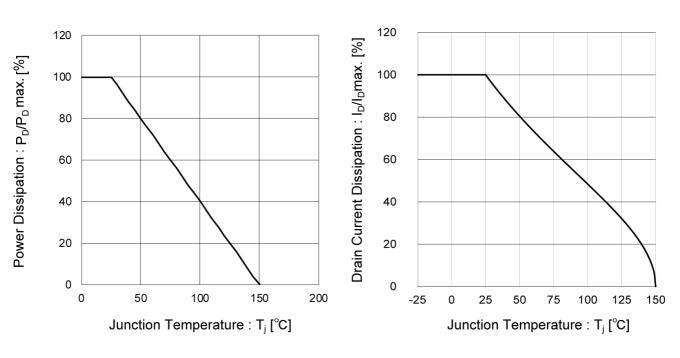


Fig.1 Power Dissipation Derating Curve

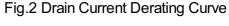


Fig.3 Transient Thermal Resistance vs. Pulse Width

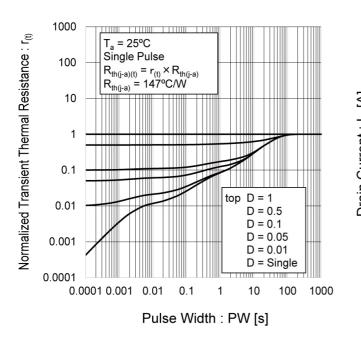
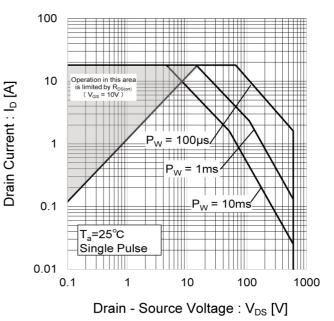


Fig.4 Maximum Safe Operating Area





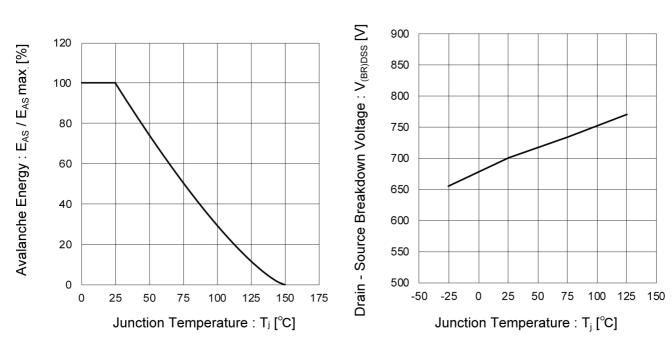


Fig.5 Avalanche Energy DeratingCurve vs. Junction Temperature

Fig.6 Breakdown Voltage vs. Junction Temperature

Fig.7 Typical Output Characteristics(I)

Drain Current : I<sub>D</sub> [A]

6

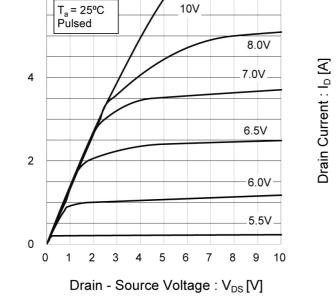


Fig.8 Typical Output Characteristics(II)

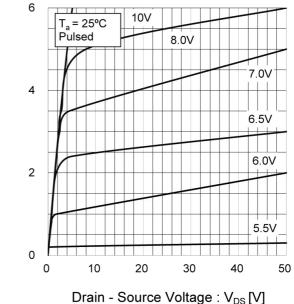
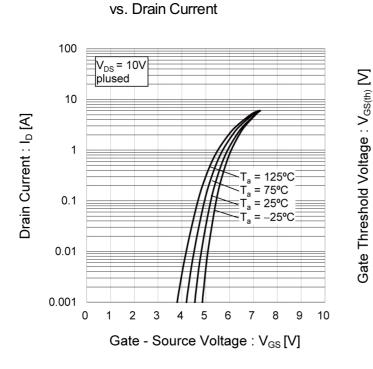
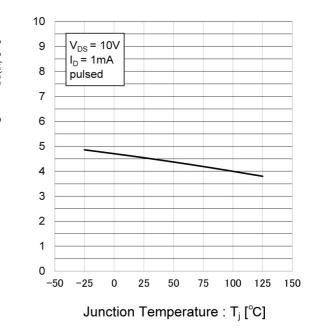




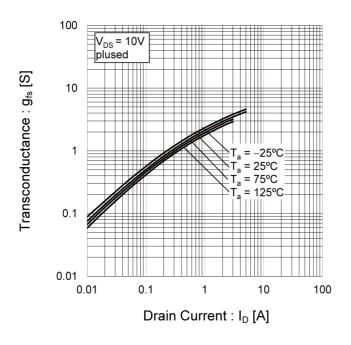
Fig.9 Gate Threshold Voltage



# Fig.10 Gate Threshold Voltage vs. Junction Temperature



# Fig.11 Forward Transfer Admittance vs. Drain Current





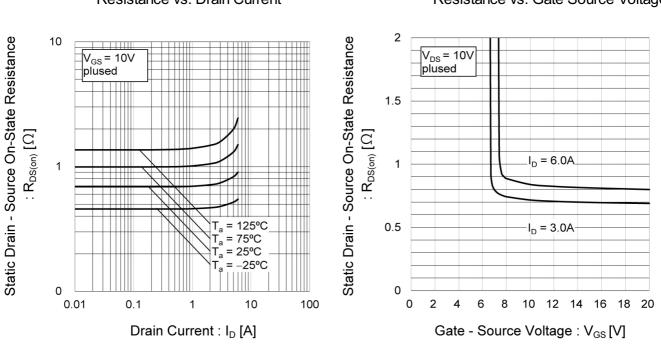


Fig.12 Static Drain - Source On - State Resistance vs. Drain Current Fig.13 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

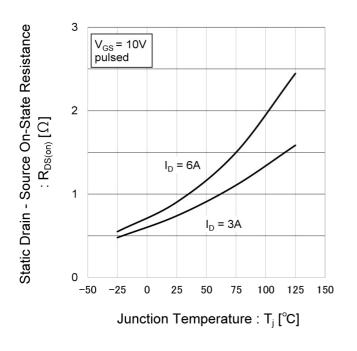
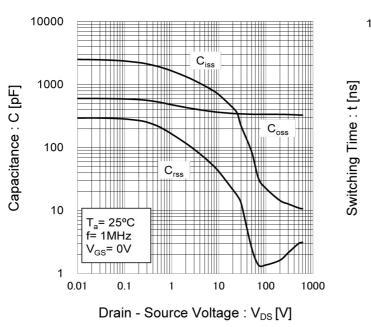


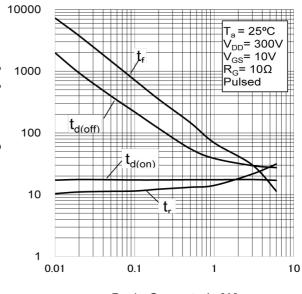


Fig.15 Typical Capacitance



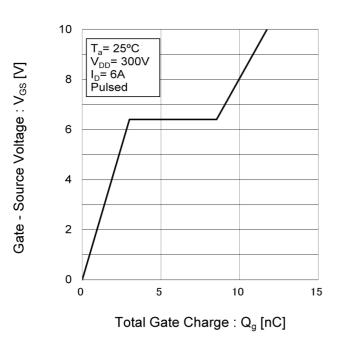
vs. Drain - Source Voltage

#### Fig.16 Switching Characteristics



Drain Current : I<sub>D</sub> [A]

Fig.17 Typical Gate Charge





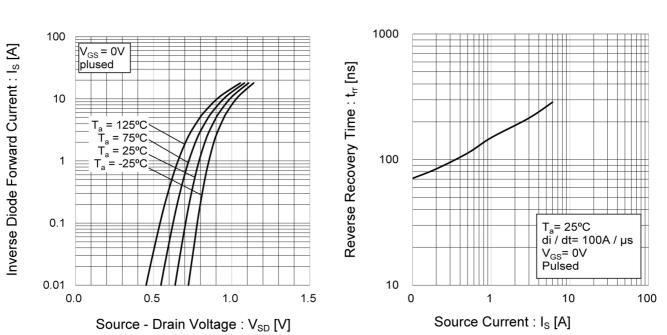


Fig.18 Source Current vs. Source - Drain Voltage Fig.19 Reverse Recovery Time vs. Source Current



#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

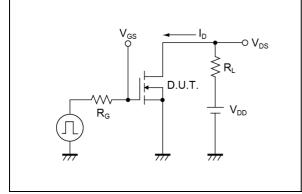
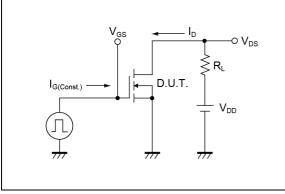


Fig.2-1 Gate Charge Measurement Circuit



#### Fig.3-1 Avalanche Measurement Circuit

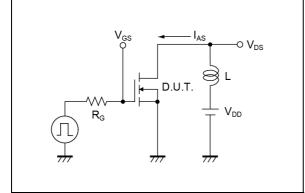
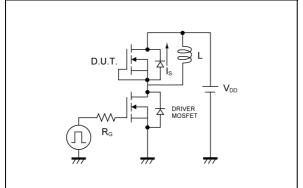
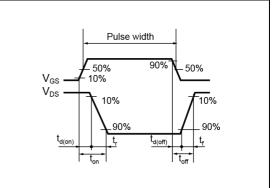


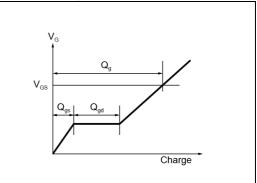
Fig.4-1 Reverse Recovery Time Measurement Circuit



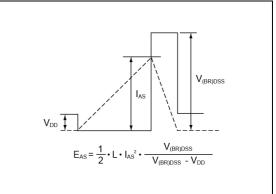
#### Fig.1-2 Switching Waveforms



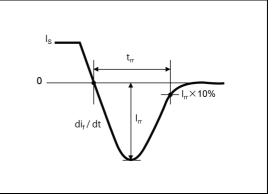
#### Fig.2-2 Gate Charge Waveform



#### Fig.3-2 Avalanche Waveform

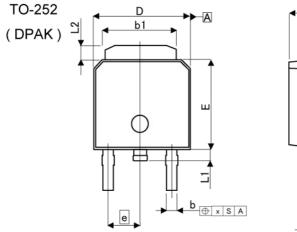


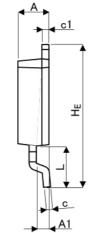
#### Fig.4-2Reverse Recovery Time Waveform

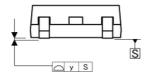


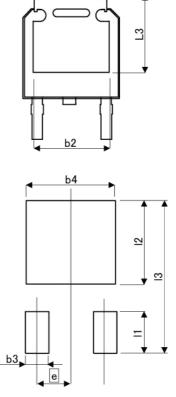


#### Dimensions









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIN	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	5.	35	0.2	11
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	70	0.1	06
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	:09
х	-	0.25	-	0.010
У	-	0.10	-	0.004

DIM MILIME		ETERS	INCHES	
	MIN	MAX	MIN	MAX
b3	<u> </u>	1.15	<u> </u>	0.045
b4	-	5.55	-	0.219
1	-	2.77	2	0.109
12	-	5.50	-	0.217
13	-	10.40	-	0.409

Dimension in mm/inches



# Notice

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1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications
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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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- 3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in an y way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.



# R6006KND3 - Web Page

**Distribution Inventory** 

Part Number	R6006KND3
Package	TO-252
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes